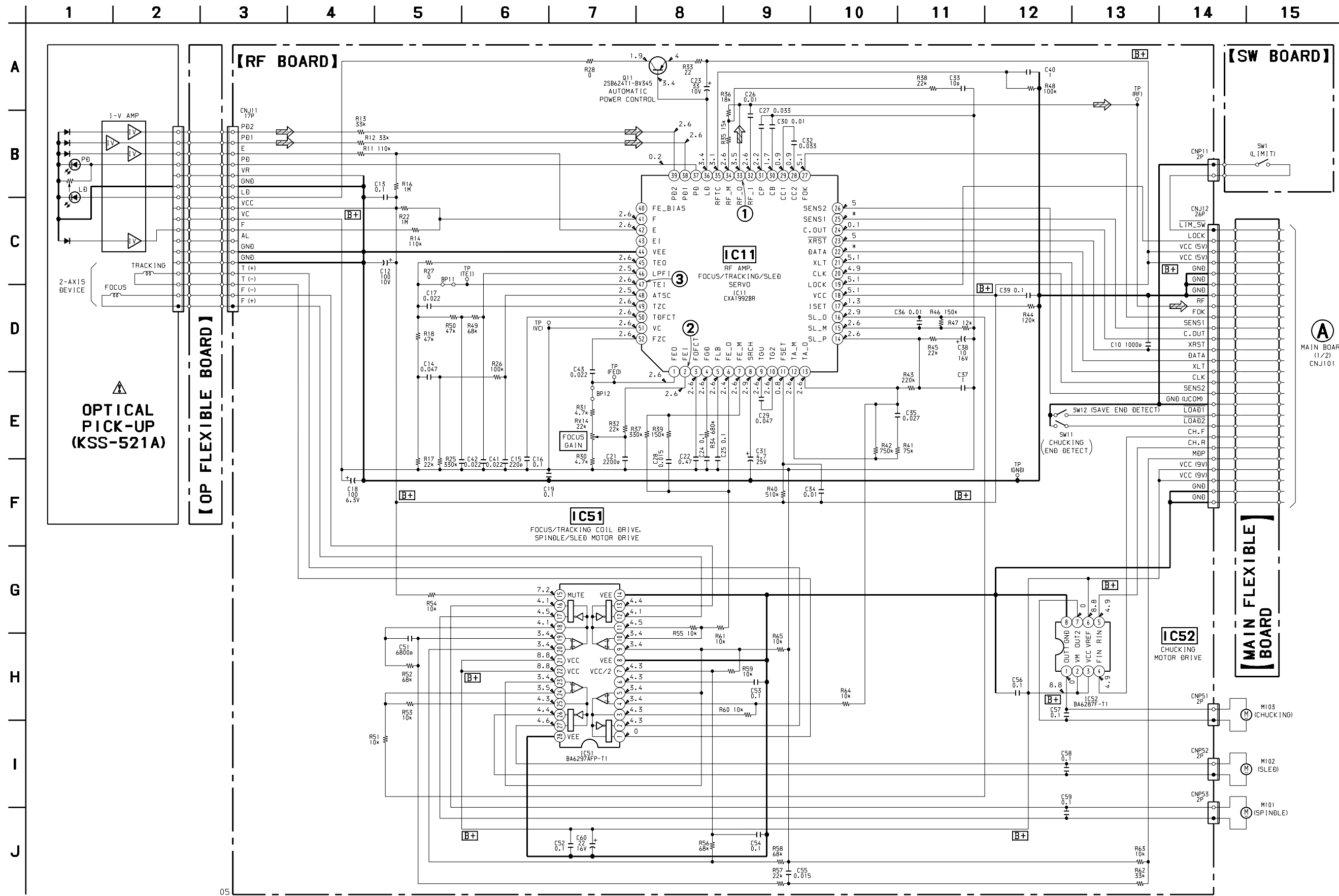


7-3. SCHEMATIC DIAGRAM – RF Section – • See page 31 for Waveforms. • See page 32 for IC Block Diagrams.



(Page 27)
MAIN BOARD
(1/2)
CNJ101

The components identified by mark Δ or dotted line with mark Δ are critical for safety. Replace only with part number specified.

Les composants identifiés par une marque Δ sont critiques pour la sécurité. Ne les remplacer que par une pièce portant le numéro spécifié.

CDX-424RF

SERVICE MANUAL

US Model
Canadian Model
E Model



Model Name Using Similar Mechanism	CDX-505RF
CD Drive Mechanism Type	MG-250C-137
Optical Pick-up Name	KSS-521A/J2N

SPECIFICATIONS

CD changer (CDX-424RF)

System	Compact disc digital audio system
Laser Diode Properties	Material: GaAlAs Wavelength: 780 nm Emission Duration: Continuous Laser out-put Power: Less than 44.6 μ W*
* This output is the value measured at a distance of 200 mm from the objective lens surface on the Optical Pick-up Block.	
Frequency response	10 – 20,000 Hz
Wow and flutter	Below than the measurable limit
Signal-to-noise ratio	94 dB
Output terminals	BUS control output terminal (8 pin) Analog audio output terminal (RCA pin)
Current drain	800 mA (at playback) 800 mA (at disc loading/ejecting)
Operating temperature	-10 °C to +55 °C (14 °F to 131 °F)
Dimensions	Approx. 262 × 90 × 181.5 mm (10 ³ / ₈ × 3 ⁵ / ₈ × 7 ¹ / ₄ in.) (w/h/d)
Mass	Approx. 2.1 kg (4 lb. 10 oz.)

Hideaway unit/

Wired remote (RM-X64)

Frequency	88.3 MHz/88.5 MHz/ 88.7 MHz/88.9 MHz/ 89.1 MHz/89.3 MHz/ 89.5 MHz/89.7 MHz/ 89.9 MHz (switchable)
Dimensions	Hideaway unit: Approx. 124.8 × 30.0 × 99.8 mm (5 × 1 ³ / ₁₆ × 4 in.) (w/h/d) Wired remote: Approx. 148 × 30 × 15 mm (5 ⁷ / ₈ × 1 ³ / ₁₆ × 1 ⁹ / ₃₂ in.) (w/h/d)
Mass	Hideaway unit: Approx. 330 g (11.64 oz.) Wired remote: Approx. 120 g (4.2 oz.)

Supplied accessories

Disc magazine (1)
Parts for installation and connections (1 set)

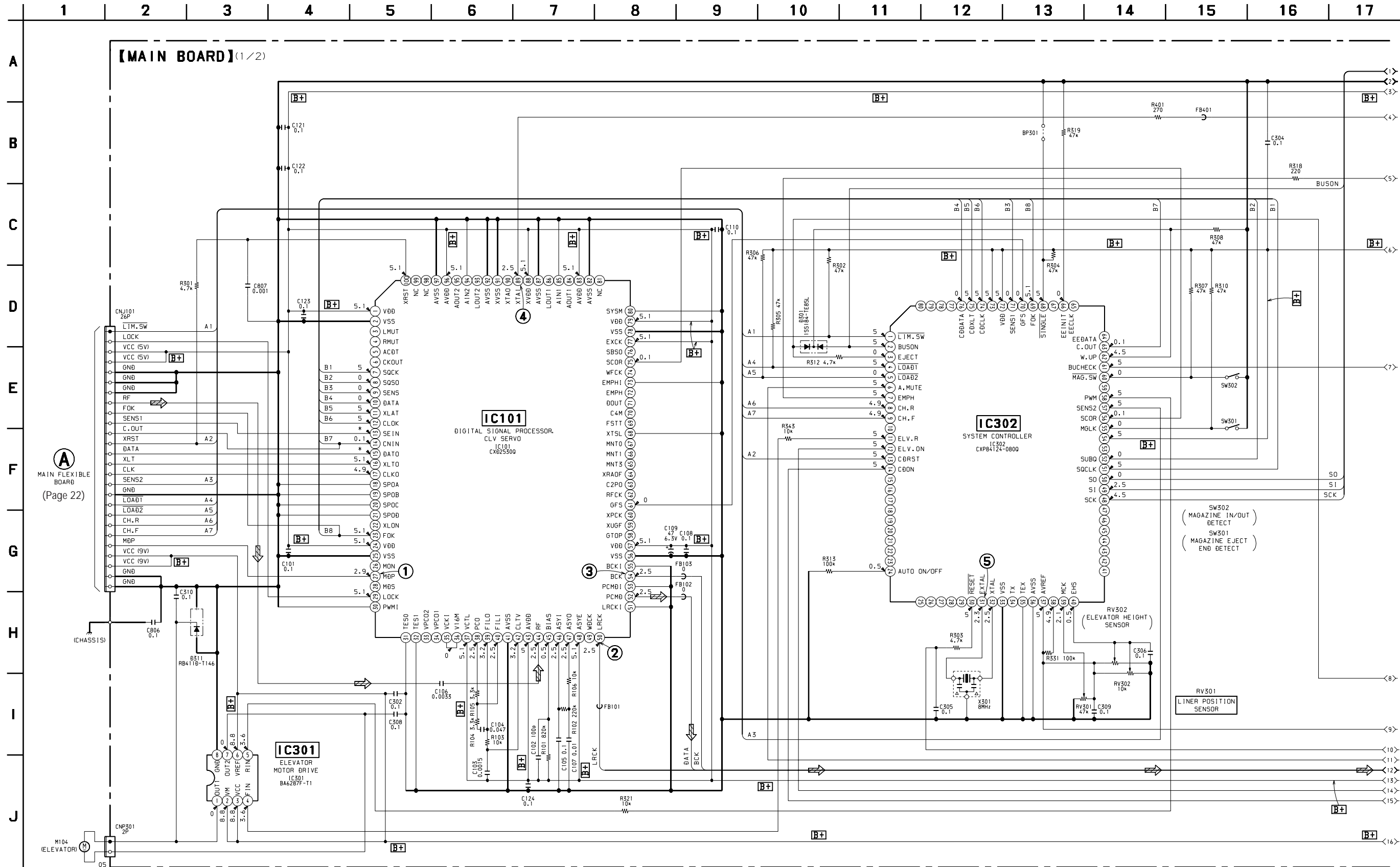
Design and specifications subject to change without notice.

COMPACT DISC CHANGER SYSTEM

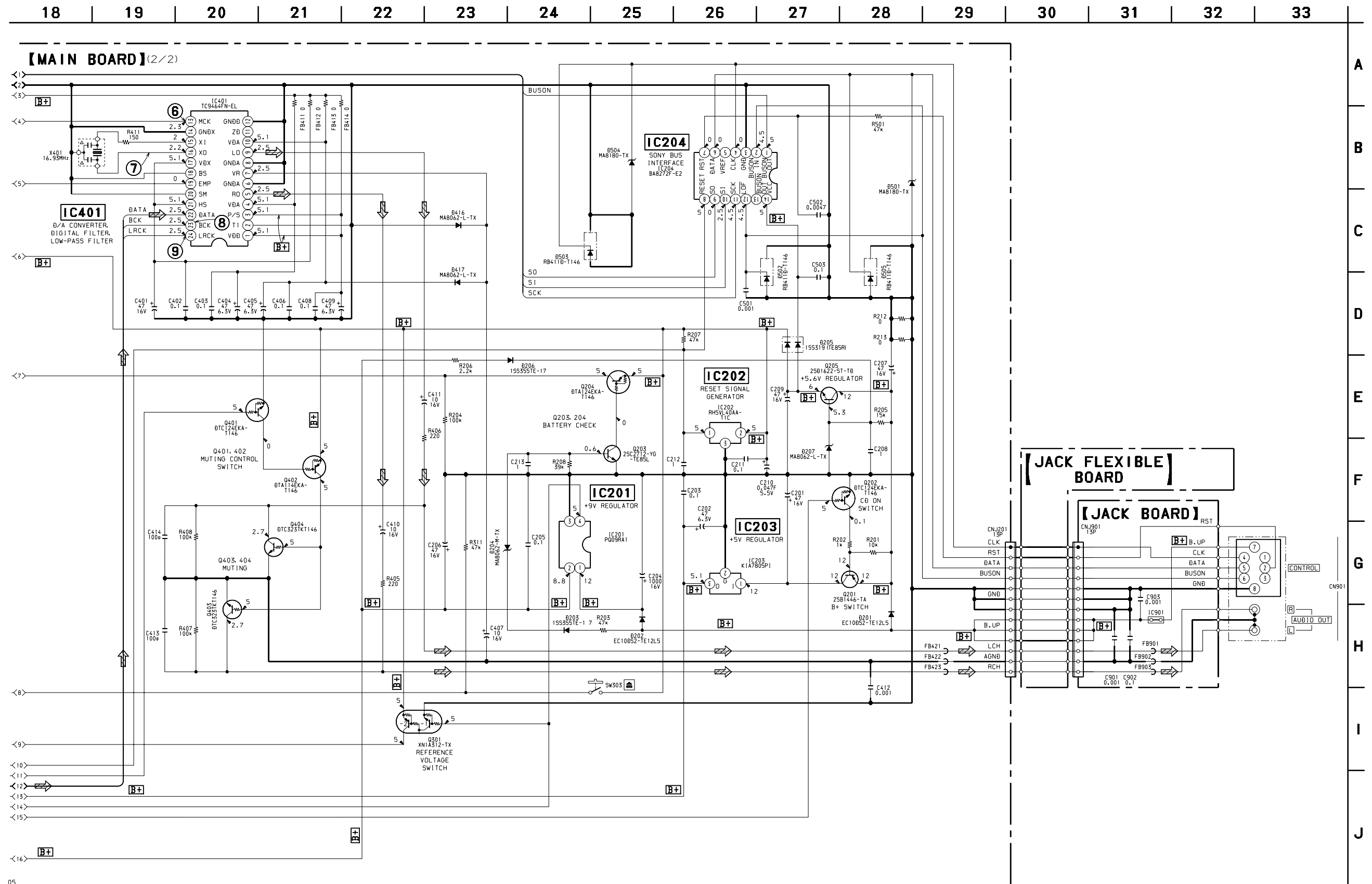


SONY®

7-6. SCHEMATIC DIAGRAM – MAIN Section (1/2) – • See page 31 for Waveforms. • See page 33 for IC Block Diagrams.

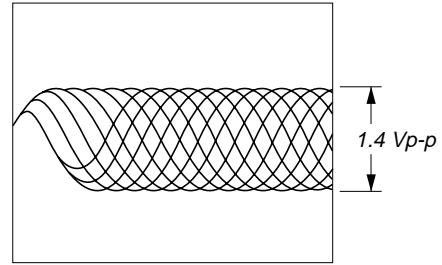


7-7. SCHEMATIC DIAGRAM – MAIN Section (2/2) – • See page 31 for Waveforms. • See page 33 for IC Block Diagrams.

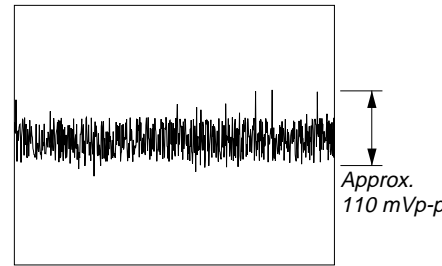


• Waveforms
– RF Board –

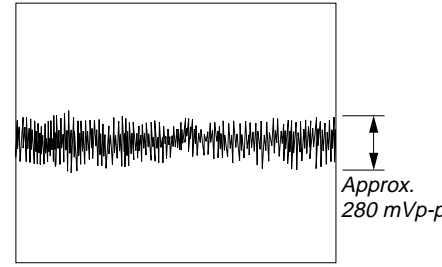
1 IC11 ③ (RF O)
500 mV/DIV, 500 ns/DIV



2 IC11 ② (FEI)
50 mV/DIV, 1 μs/DIV

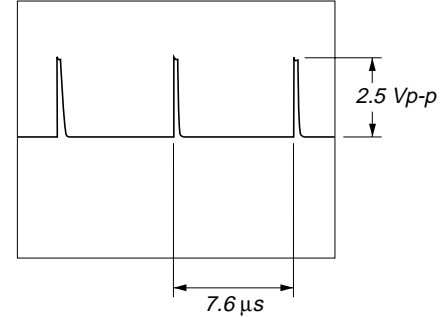


3 IC11 ④ (TEI)
200 mV/DIV, 500 μs/DIV

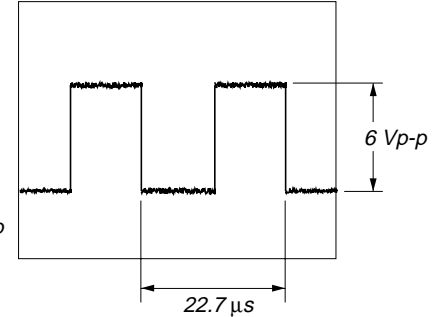


– MAIN Board (1/2) –

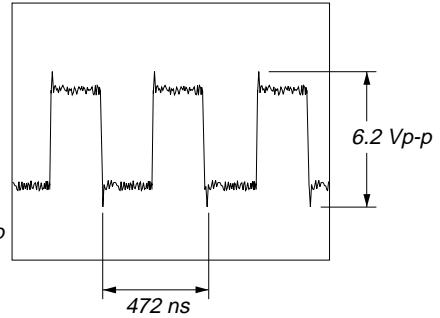
1 IC101 ② (MDP)



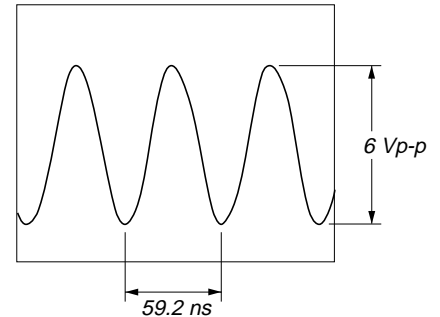
2 IC101 ⑤ (LRCK)



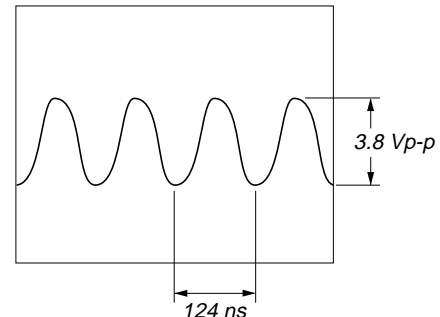
3 IC101 ⑥ (BCK)



4 IC101 ⑧ (XTAI)

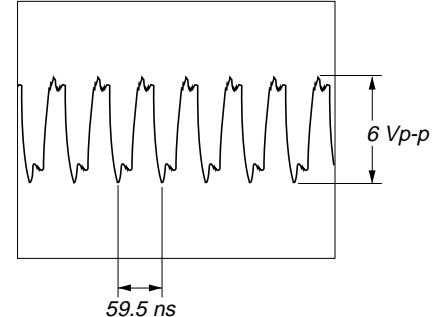


5 IC302 ③ (EXTAL)

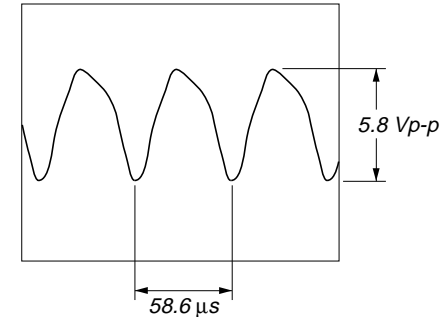


– MAIN Board (2/2) –

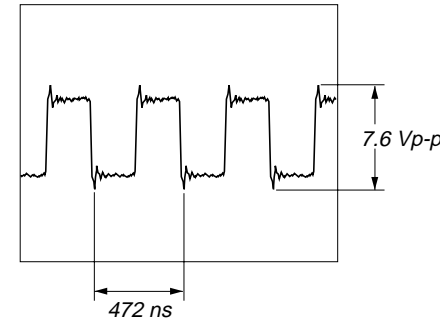
6 IC401 ⑬ (MCK)



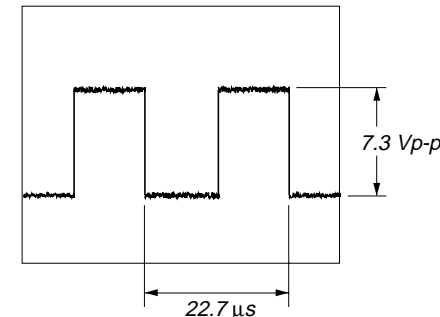
7 IC401 ⑮ (XO)



8 IC401 ⑲ (BCK)

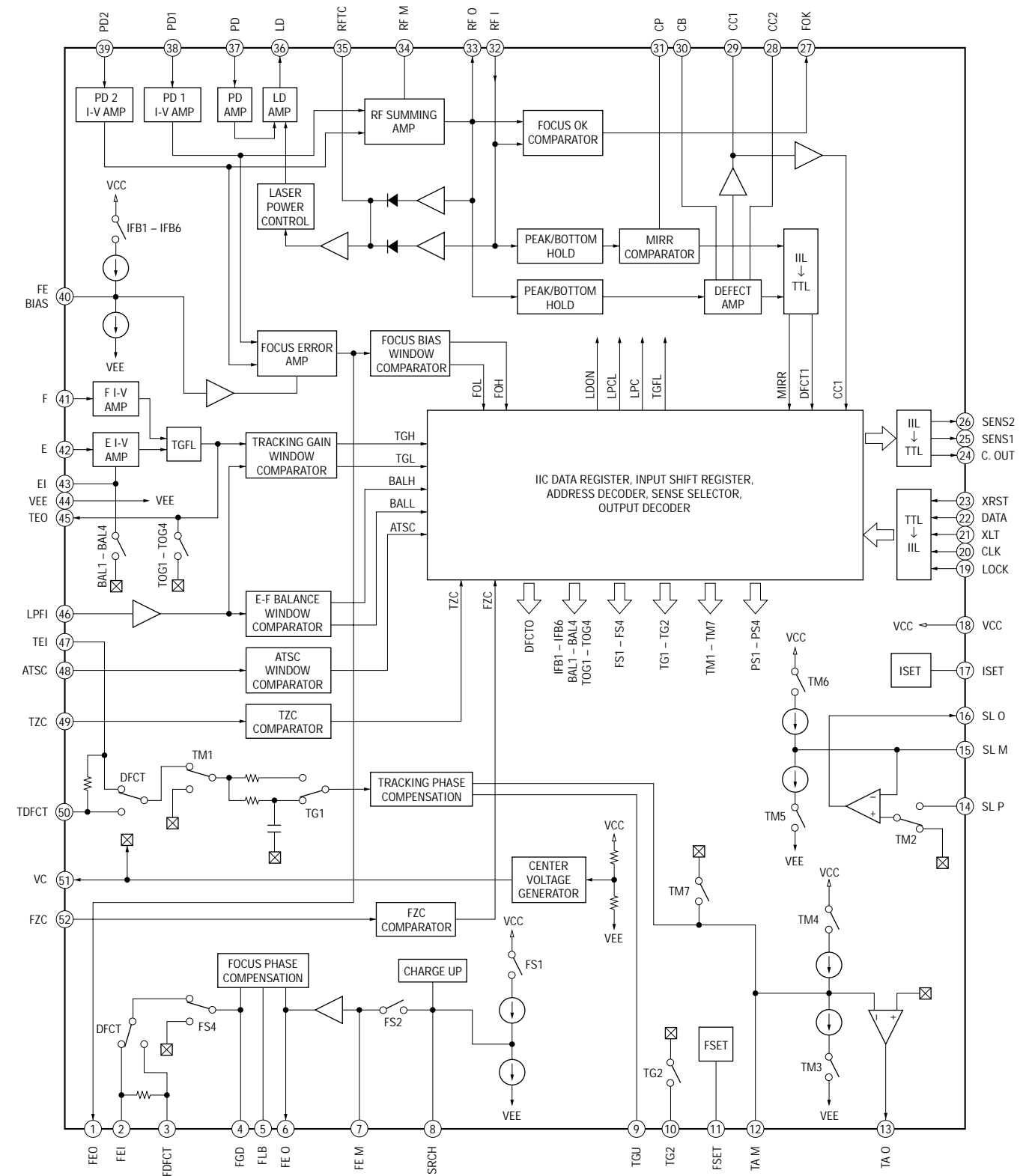


9 IC401 ⑳ (LRCK)

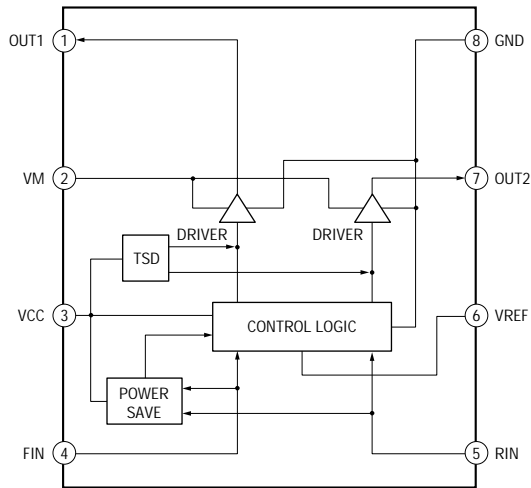


• IC Block Diagrams
– RF Board –

IC11 CXA1992BR

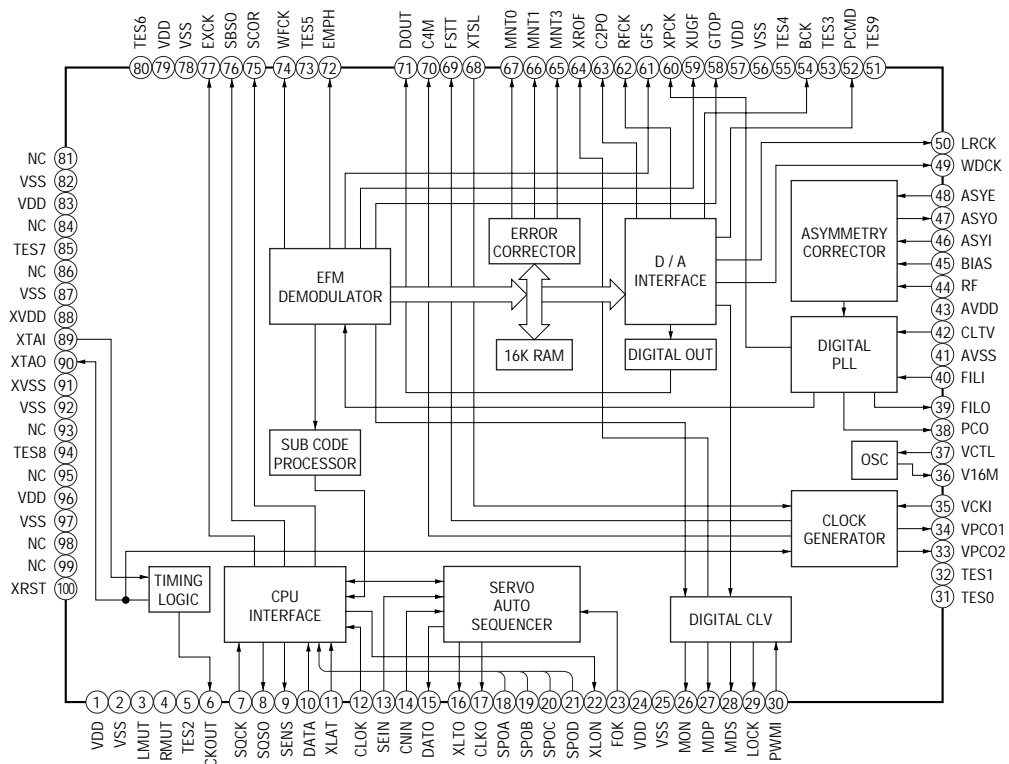


IC52 BA6287F

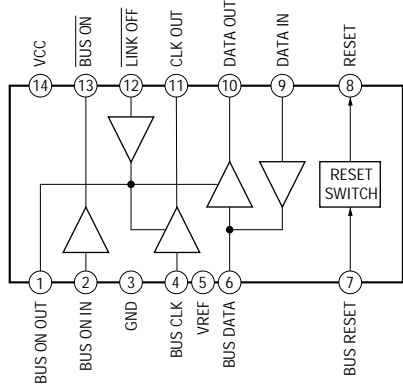


- MAIN Board -

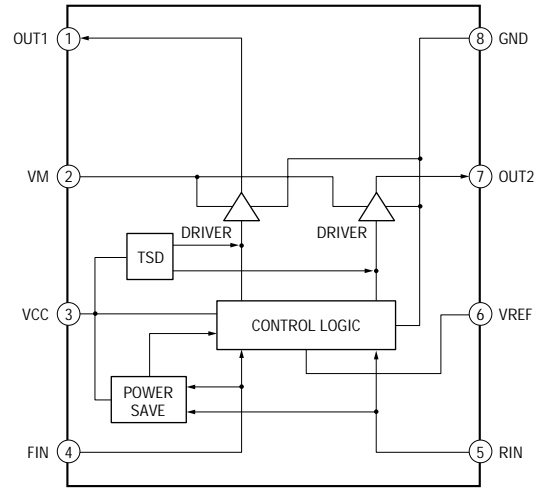
IC101 CXD2530Q



IC204 BA8272F-E2



IC301 BA6287F



IC401 TC9464FN-EL

